



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁷ : C08K 3/04, C08L 67/06	A1	(11) International Publication Number: WO 00/49076 (43) International Publication Date: 24 August 2000 (24.08.00)
(21) International Application Number: PCT/US00/04262 (22) International Filing Date: 18 February 2000 (18.02.00) (30) Priority Data: 60/120,677 19 February 1999 (19.02.99) US (71) Applicant (for all designated States except US): UNION CARBIDE CHEMICALS & PLASTICS TECHNOLOGY CORPORATION [US/US]; 39-Old Ridgebury Road, Danbury, CT 06817-0001 (US). (71)(72) Applicant and Inventor: REX, Gary, Charles [US/US]; 5307 Stephen Way, Cross Lanes, WV 25313 (US). (74) Agent: PACCIONE, Stanley, Jesson; Union Carbide Chemicals & Plastics Technology Corporation, 39-Old Ridgebury Road, Danbury, CT 06817-0001 (US).	(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, TJ, TM, TR, TT, UA, UG, US, UZ, VN, ZA, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>	
(54) Title: CONDUCTIVE MOLDING COMPOSITIONS AND ARTICLES MOLDED THEREFROM		
(57) Abstract Electrically conductive, thermoset molding compositions are disclosed which comprise an unsaturated thermosetting resin, an olefinically unsaturated monomer which is copolymerizable with the thermosetting resin, a thermoplastic additive and carbon black. The carbon black is incorporated in a conductive additive which comprises the thermoplastic additive, the carbon black and, preferably, a lubricant. The electrical resistance of articles molded from the disclosed molding compositions is typically less than about 10 ⁸ ohms/cm ² .		